

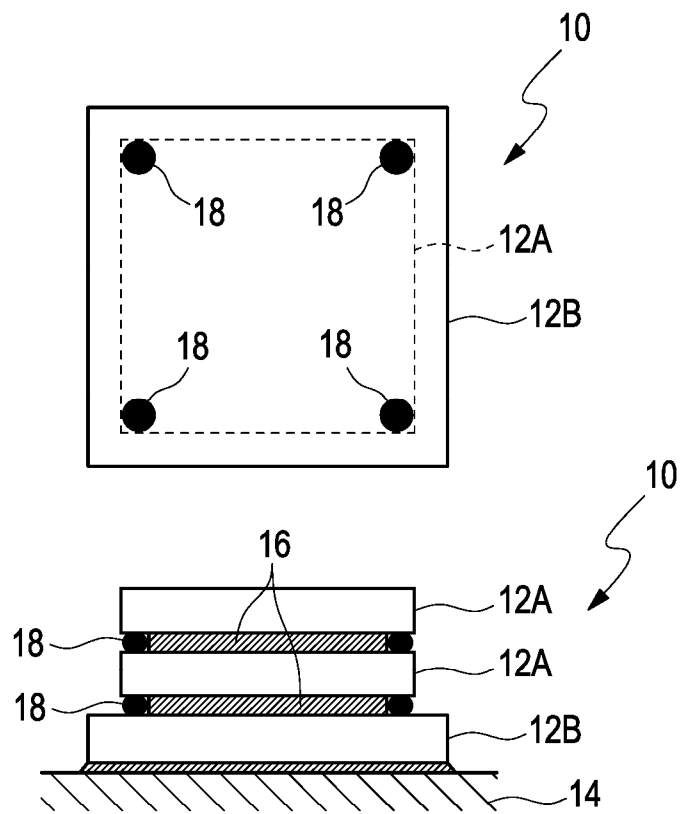


Fig. 1

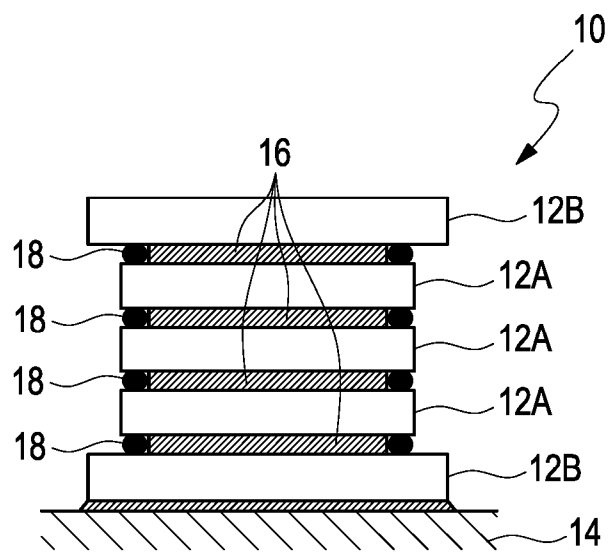


Fig. 2

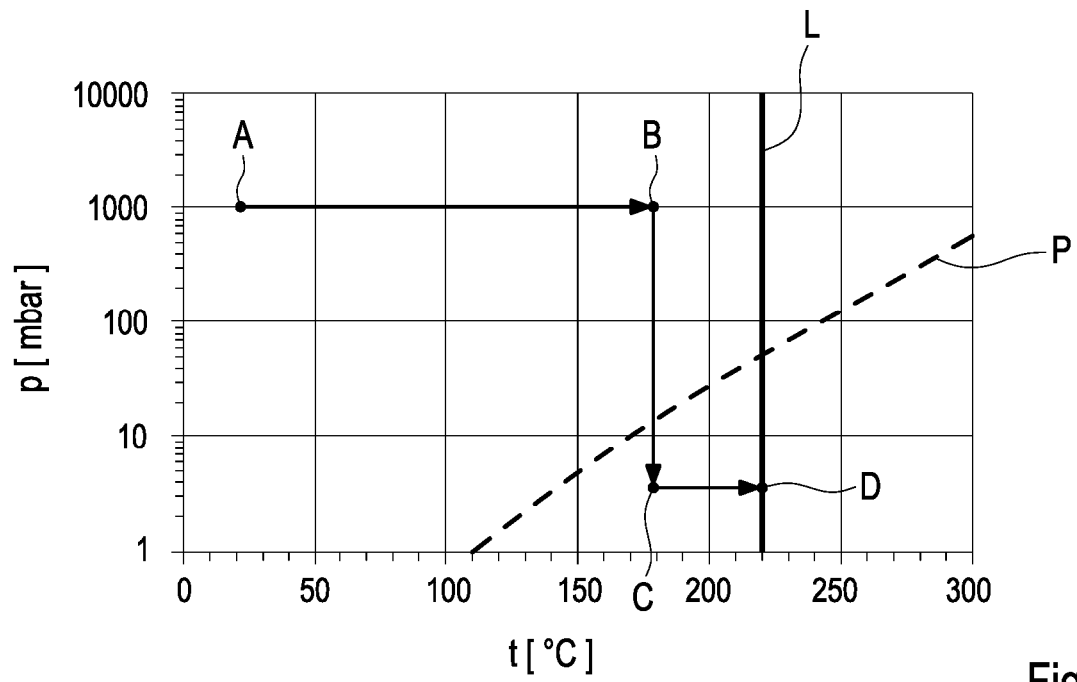


Fig. 3

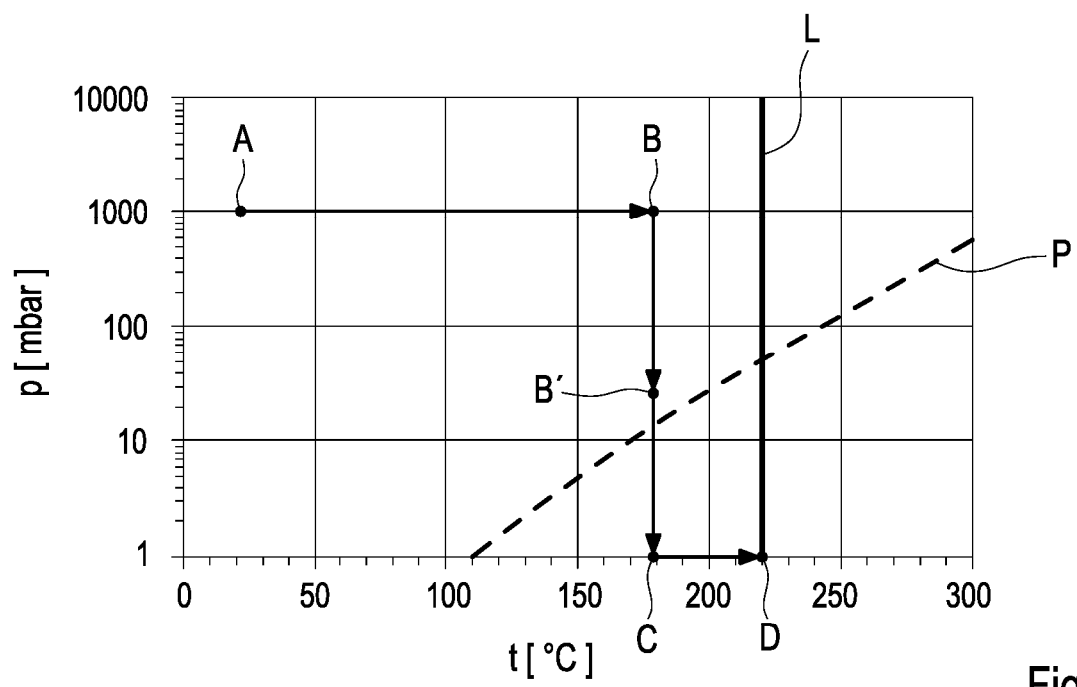


Fig. 4

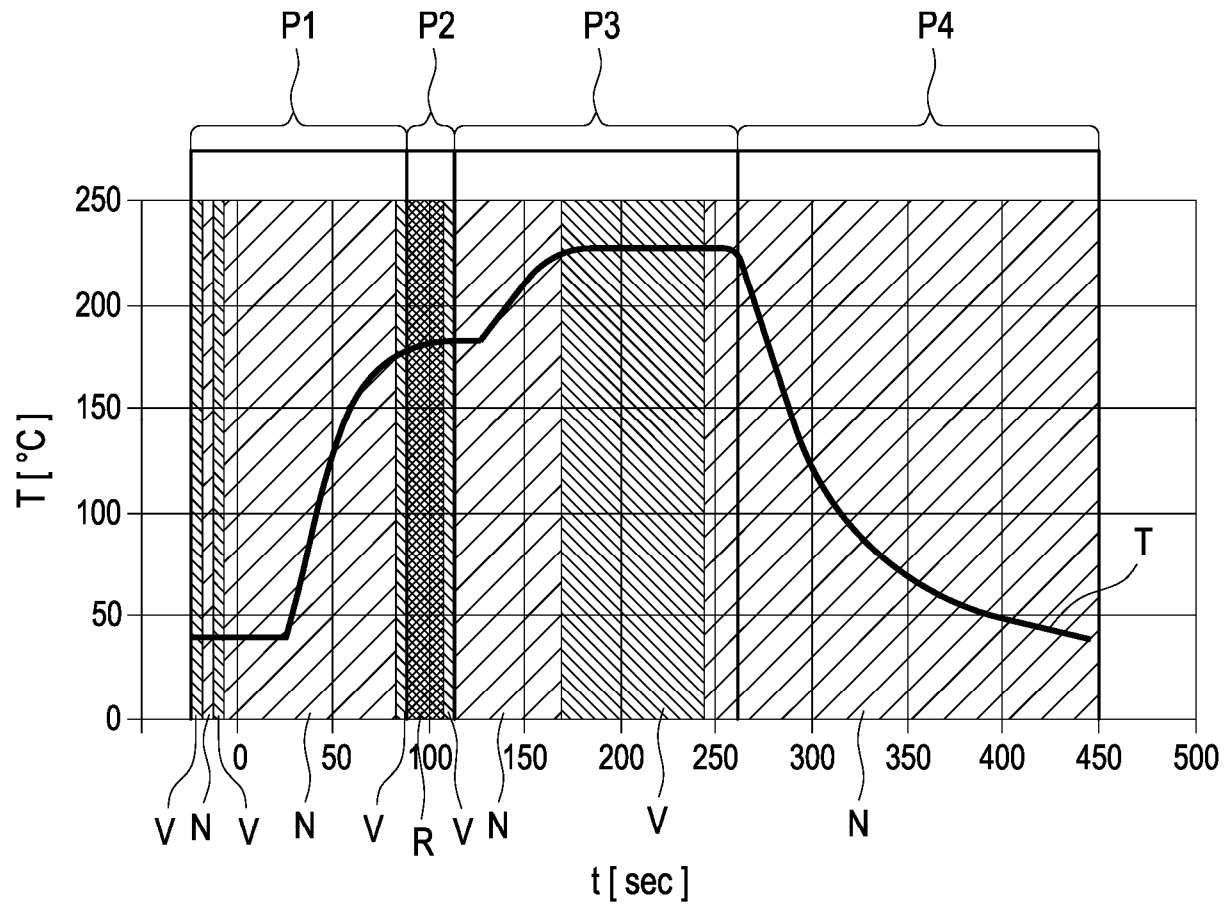


Fig. 5

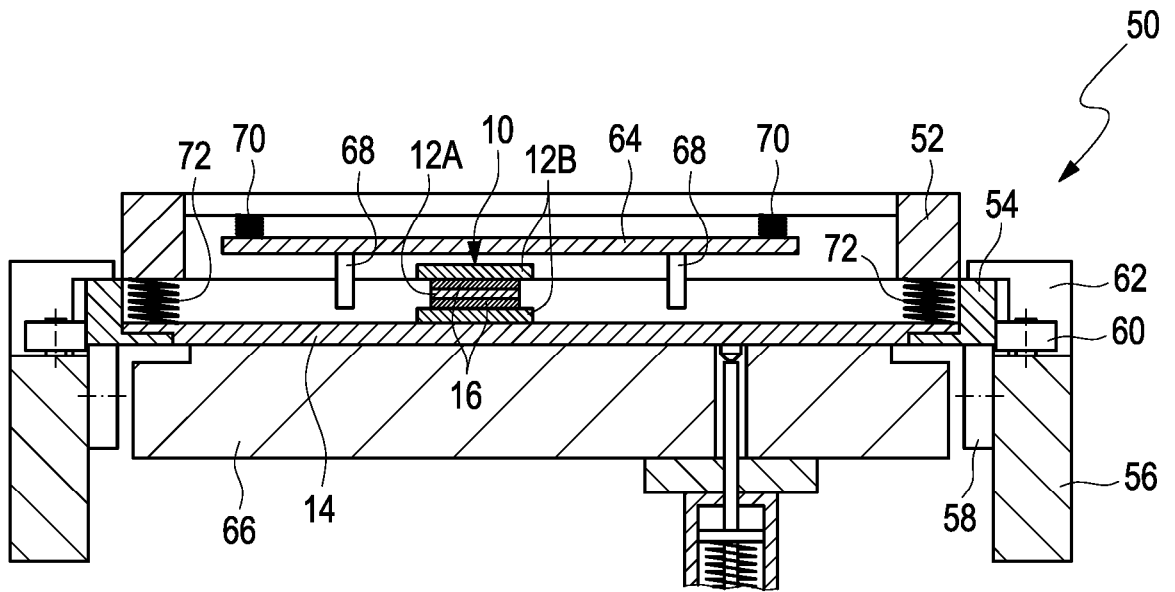


Fig. 6

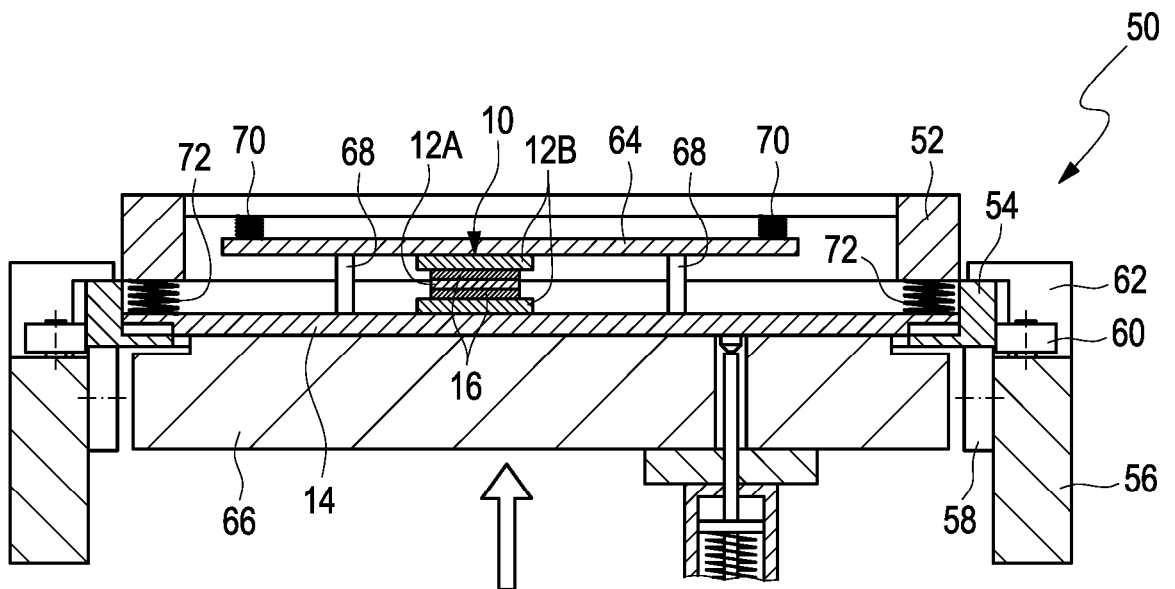


Fig. 7

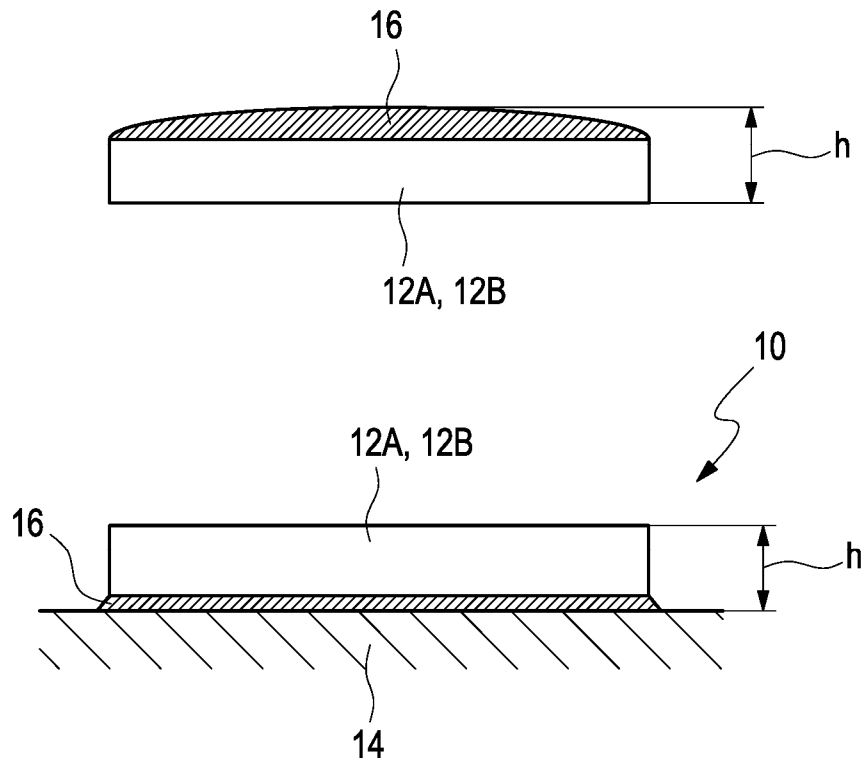
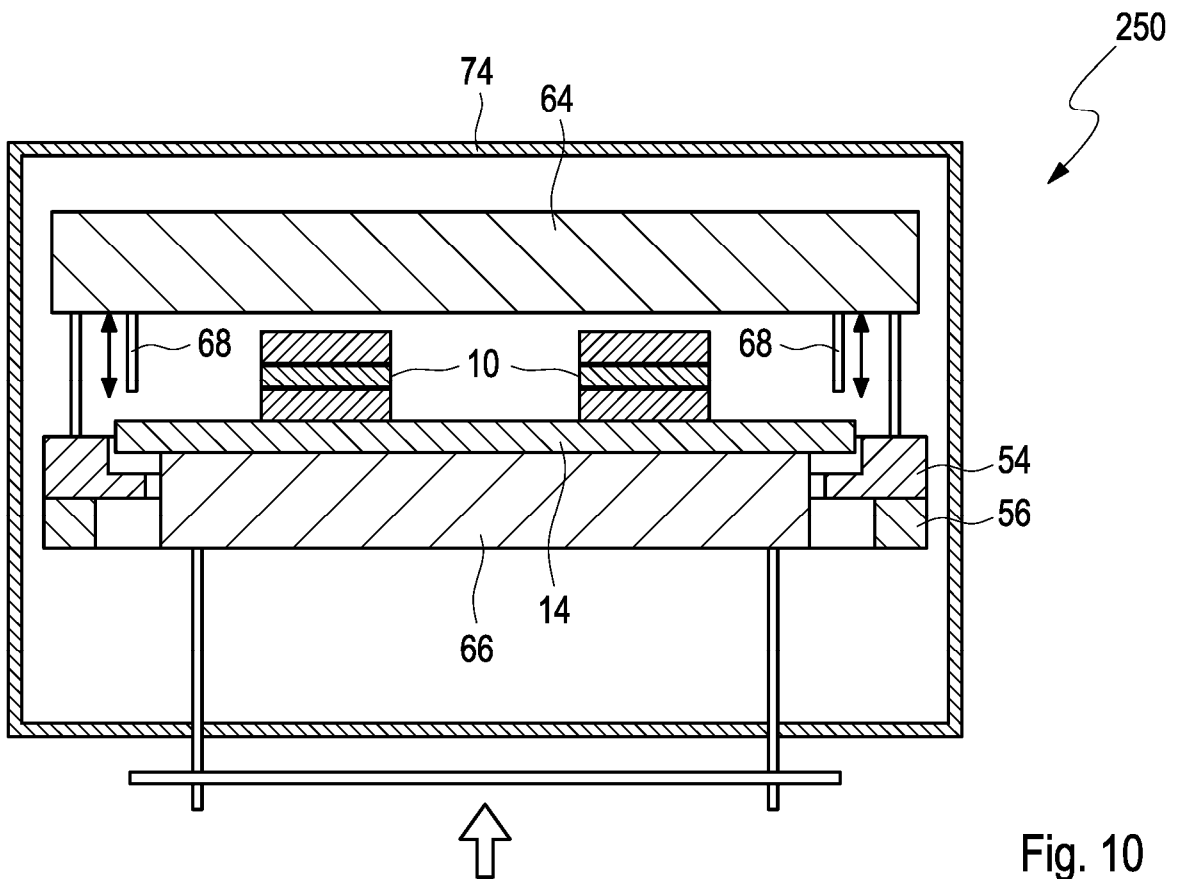
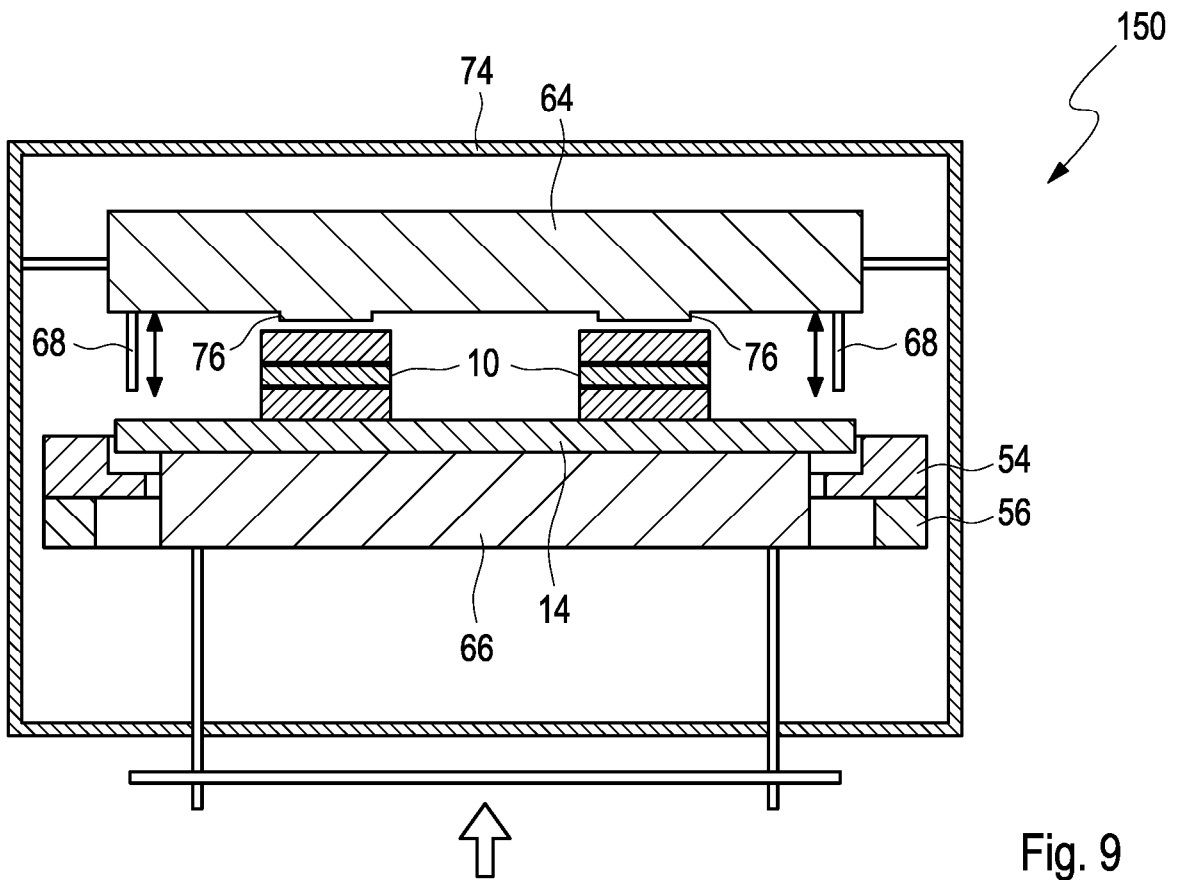


Fig. 8

6/10



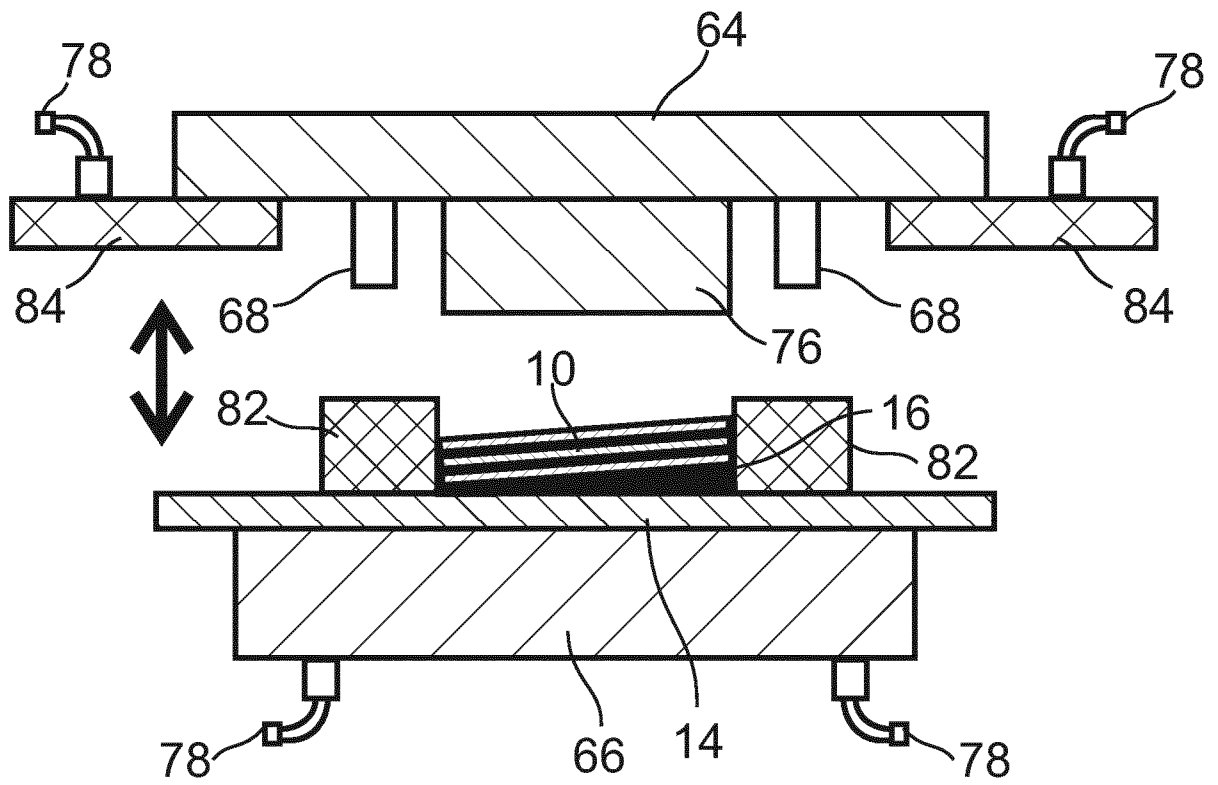


Fig. 11a

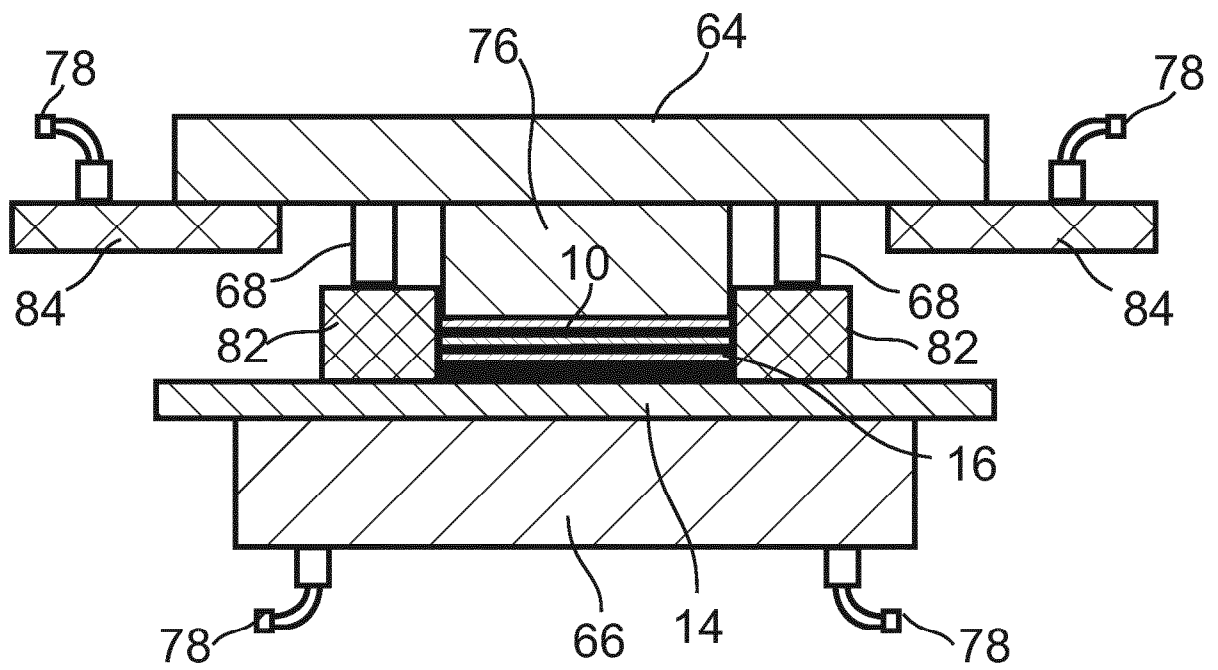


Fig. 11b

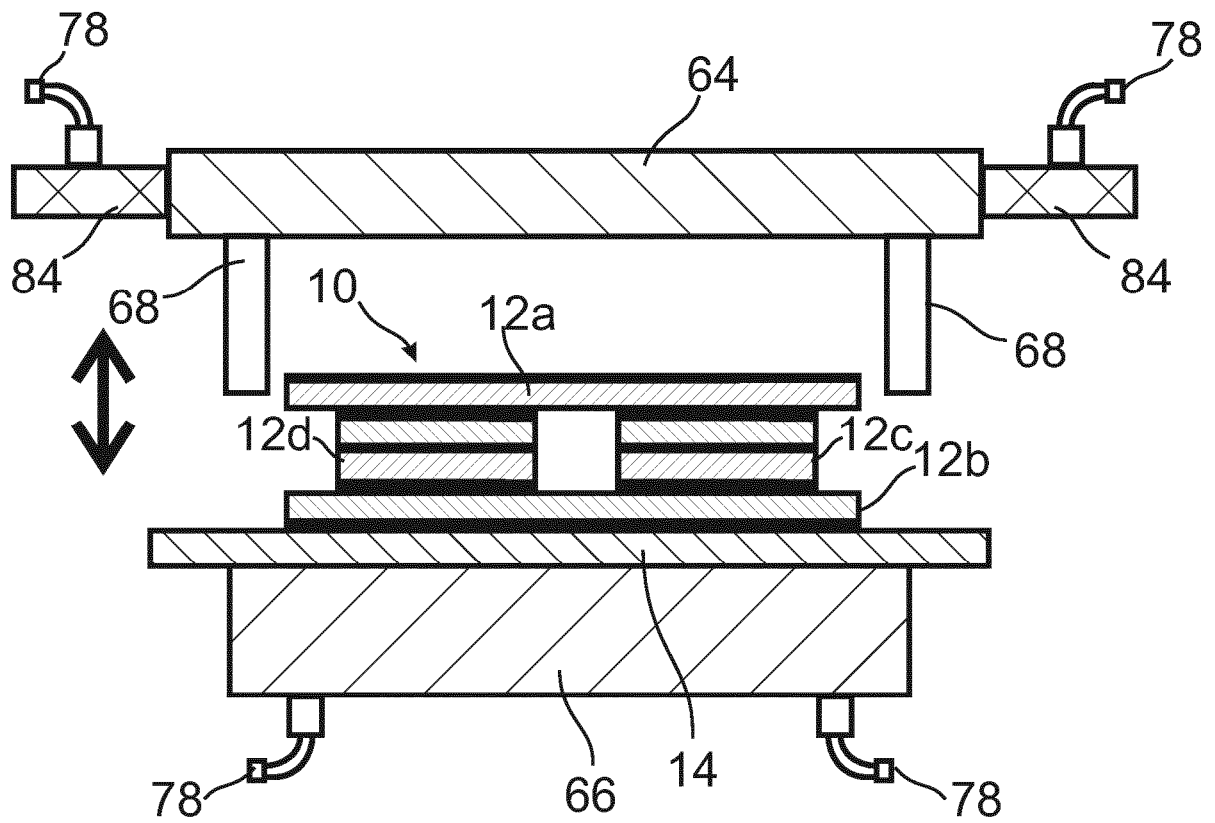


Fig. 12a

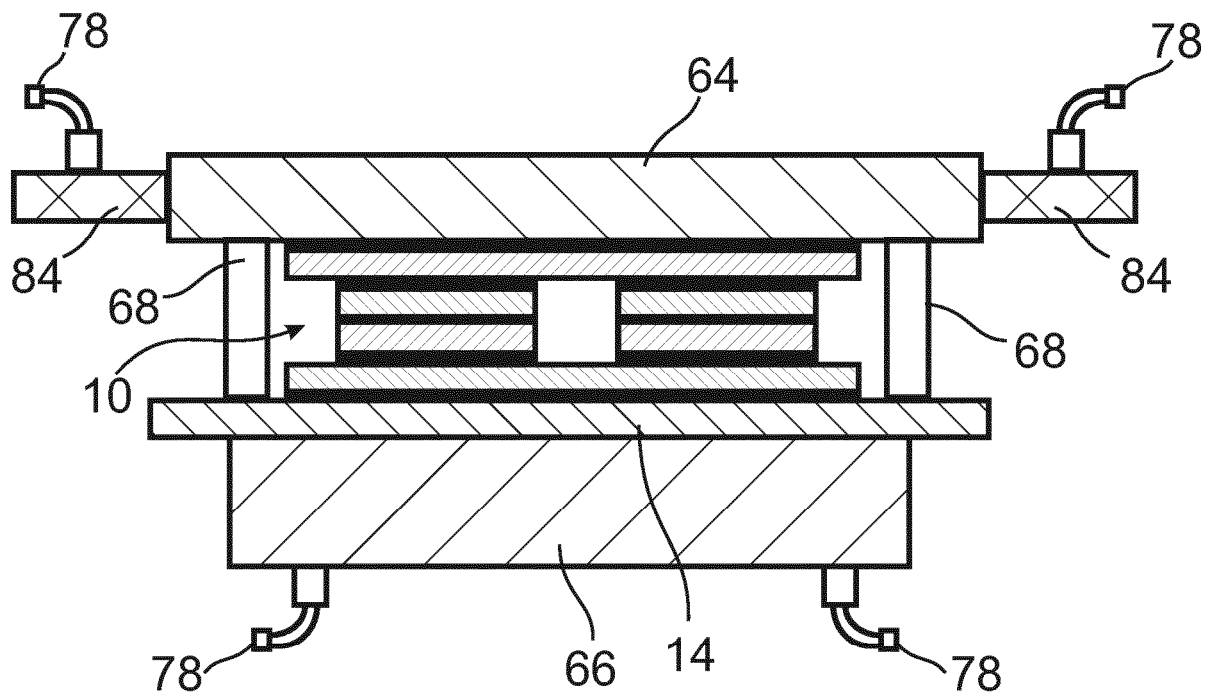
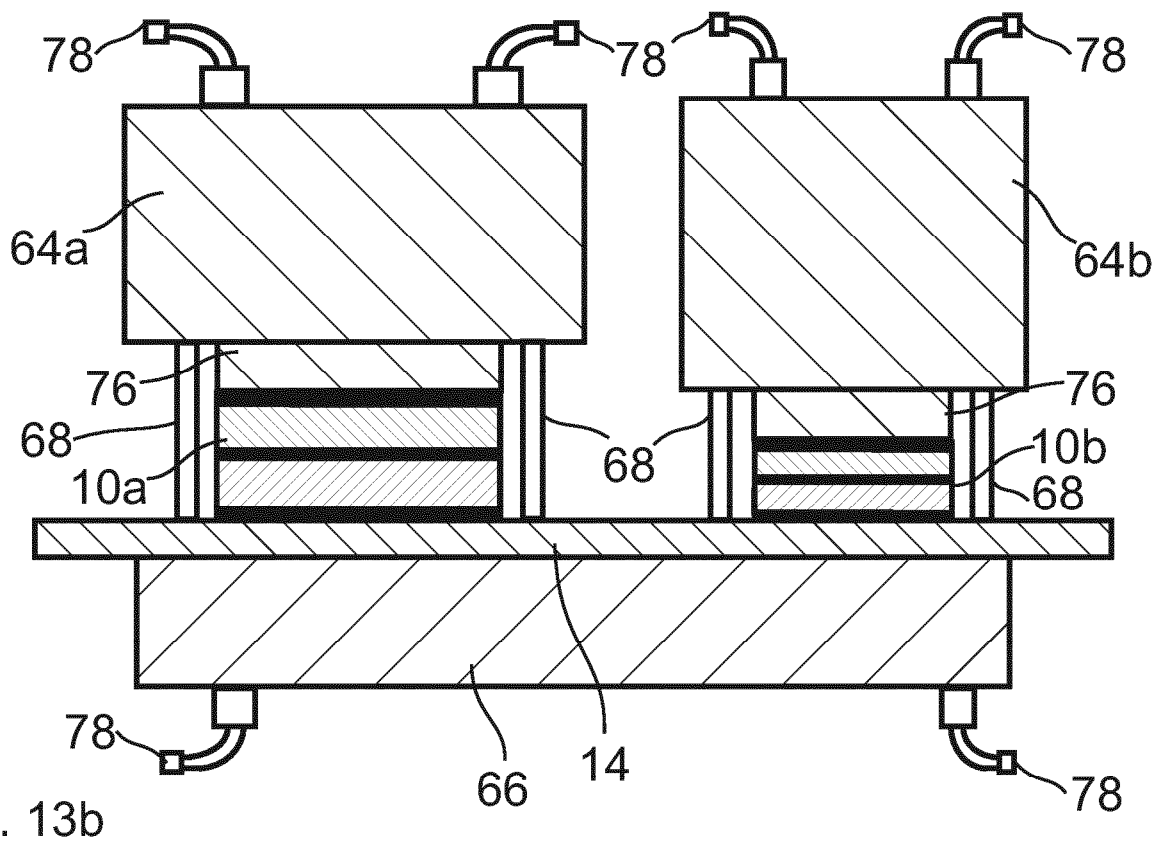
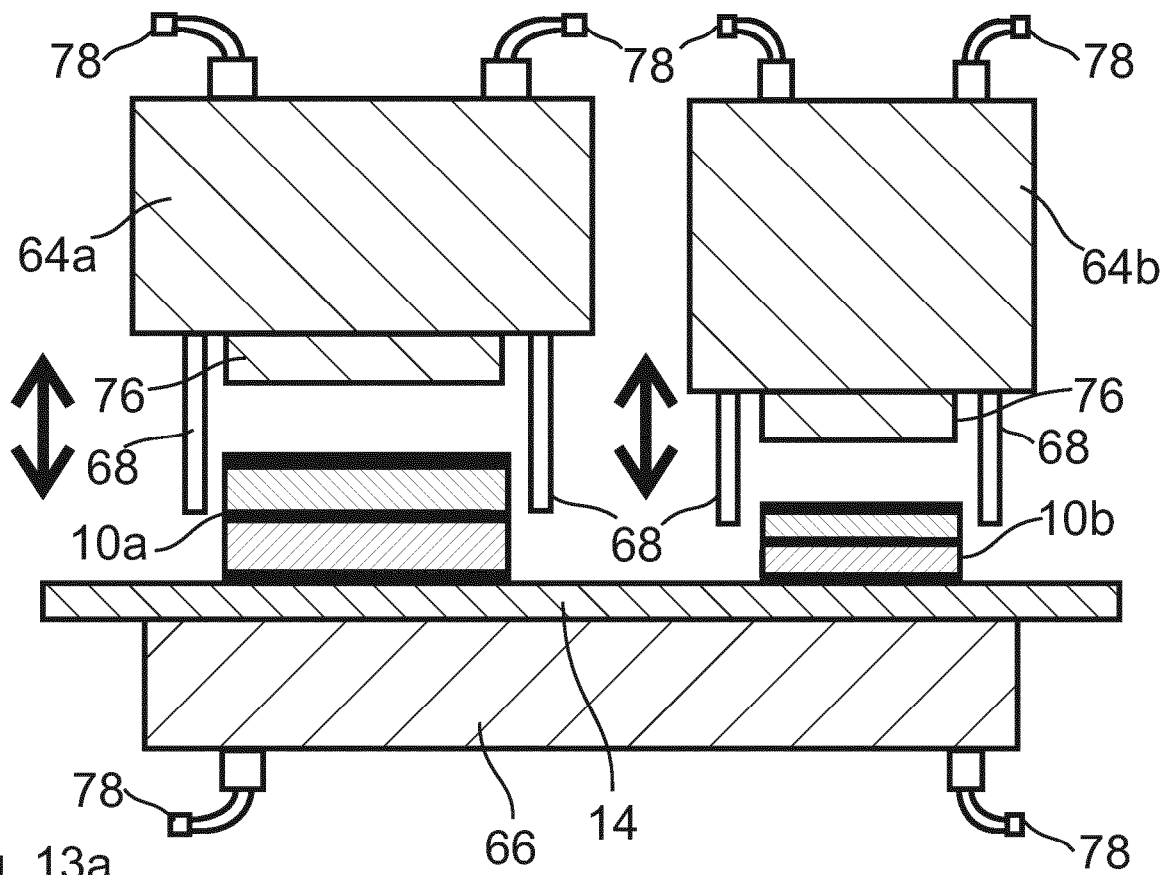


Fig. 12b



A cross-sectional view of a device assembly 10. The assembly includes a top layer 64, a central cavity 14, and a bottom layer 66. The cavity 14 contains a central block 10 and a smaller block 12. The top layer 64 is connected to a side layer 84, which is further connected to a terminal 78. The bottom layer 66 is connected to a side layer 68, which is further connected to a terminal 78. The central block 10 is connected to a terminal 78. The side layers 68 and 76 are connected to a terminal 78. The side layers 68 and 76 are also connected to a terminal 78. The side layers 68 and 76 are also connected to a terminal 78.

Fig. 14b